L Number	Hits	Search Text	DB	Time stamp
1	4	(("5170009") or ("6245259")).PN.	USPAT;	2003/01/21 13:13
1	1	((02/0000) = ()	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
1_ 1	3	coat\$4 with (chip IC die LED) and	USPAT;	2003/01/14 13:33
	_	(amorphous adj fluororesin)	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
_	71	amorphous adj fluororesin	USPAT;	2003/01/14 13:33
]			US-PGPUB;	
			EPO; JPO;	
	İ		DERWENT;	
ļ			IBM_TDB	2003/01/14 13:34
-	6	•	USPAT;	2003/01/14 13:34
ļ		die LED)	US-PGPUB;	1
			EPO; JPO;	ļ
			DERWENT;	
			IBM_TDB	2003/01/16 15:39
-	71		USPAT; US-PGPUB;	2003/01/10 13.39
		and coat\$4	EPO; JPO;	
			DERWENT;	
			IBM TDB	
		TO TEN	USPAT;	2003/01/14 13:40
-	61	257/294.ccls. and (chip die IC LED)	US-PGPUB;	2003/01/13 13.30
i			EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
		osayooo ooo aala and /ohin die TC IED)	USPAT;	2003/01/14 13:45
-	354	257/290-292.ccls. and (chip die IC LED)	US-PGPUB;	2000, 02, 20
i			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
	4	(("6051848") or ("6274890")).PN.	USPAT;	2003/01/14 13:47
_	4	((6031848) 01 (0274030)).12	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	1
_	2027	257/88,91,94-100.ccls. and (chip die LED	USPAT;	2003/01/14 13:51
	202,	IC)	US-PGPUB;	
			EPO; JPO;	
	ļ		DERWENT;	
			IBM_TDB	
-	3	257/88,91,94-100.ccls. and (chip die LED	USPAT;	2003/01/14 13:50
1		IC) and ((amorphous adj fluororesin) PTFE)	US-PGPUB;	
1			EPO; JPO;	
1			DERWENT;	
	1		IBM_TDB	2003/01/14 13:52
-	2027	257/88,91,94-100.ccls. and (chip die LED	USPAT;	2003/01/14 13:32
	1.	IC)	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT; IBM TDB	1
		1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT;	2003/01/14 16:00
-	284	257/88,91,94-100.ccls. and (chip die LED		2003,01/14 10.00
		IC) and lead and resin	US-PGPUB; EPO; JPO;	1
ļ	1		DERWENT;	
			IBM TDB	1
	JAN 2	057/666 600 600 600 707 700 700 6010 603	USPAT;	2003/01/14 16:13
-	2408	257/666,690,692-693,787-788,790.ccls. and	US-PGPUB;	
		(chip die LED IC) and lead and resin	EPO; JPO;	
1	1		DERWENT;	1
	1		IBM TDB	
1	1	257/666,690,692-693,787-788,790.ccls. and	USPAT;	2003/01/14 16:51
-	423	(chip die LED IC) with coat\$4 and lead and	US-PGPUB;	
1		resin	EPO; JPO;	
		Testii	DERWENT;	
	1		IBM TDB	
		<u> </u>		

	1	(257/\$.ccls. 438/\$.ccls.) and (amorphous	USPAT;	2003/01/14 16:53
İ		adj fluororesin) with (PTFE	US-PGPUB; EPO; JPO;	
		polytetrafluoroethylene)	DERWENT;	
			IBM_TDB	0000/01/16 15 04
-	3	(amorphous adj fluororesin) with (PTFE	USPAT; US-PGPUB;	2003/01/16 15:04
		polytetrafluoroethylene)	EPO; JPO;	
			DERWENT;	
		1 () h-11)	IBM TDB	2003/01/15 14:05
-	2620	438/612-614,108,118.ccls. and (bump ball)	USPAT; US-PGPUB;	2003/01/13 14.03
			EPO; JPO;	
			DERWENT; IBM TDB	
	170	438/612-614,108,118.ccls. and (bump ball)	USPAT;	2003/01/15 14:13
_	170	with (\$1m micrometer m)	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
_	138	438/612-614,108,118.ccls. and (bump ball)	USPAT;	2003/01/15 14:28
		with pitch and (\$1m micrometer m)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	205	438/612-614,108,118.ccls. and (bump ball)	USPAT; US-PGPUB;	2003/01/15 14:16
		with (pitch spac\$4) and (\$1m micrometer m)	EPO; JPO;	
			DERWENT;	
		and thomp holl)	IBM_TDB USPAT;	2003/01/15 15:06
-	1107	438/612-614,108,118.ccls. and (bump ball) with (layer adher\$4)	US-PGPUB;	2003/01/13 13:00
		With (layer adher 47)	EPO; JPO;	
			DERWENT; IBM TDB	
	0	("59373210").PN.	USPAT;	2003/01/15 14:34
-		(33373210)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	2	("5937320").PN.	USPAT;	2003/01/15 14:34
			US-PGPUB; EPO; JPO;	
1 // 1			DERWENT;	
			IBM_TDB	0002/01/15 14.25
-	4		USPAT	2003/01/15 14:35
_	17	"5634268").PN. 5937320.URPN.	USPAT	2003/01/15 14:35
-	502	257/733,778-779.ccls. and (bump ball) with	USPAT;	2003/01/15 15:08
		(layer adher\$4)	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB USPAT;	2003/01/15 15:08
-	73	257/733,778-779.ccls. and (bump ball) with (layer adher\$4) and (bond adj pad)	US-PGPUB;	2303,01,13 13.00
		(Tayer admery) and (Dona da) pad)	EPO; JPO;	
			DERWENT; IBM TDB	
	667	(bump ball) with (layer adher\$4) and (bond	USPAT;	2003/01/15 15:09
] -	""	adj pad)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
_	219	(bump ball) with pitch and (layer adher\$4)	USPAT;	2003/01/15 15:09
		and (bond adj pad)	US-PGPUB;	
			EPO; JPO; DERWENT;	
	1		IBM TDB	

		i li	USPAT;	2003/01/15 15:30
-	3	(bump ball) with pitch with (layer adher\$4) and (bond adj pad)	US-PGPUB;	
1		adhersa) and (bond adj pad)	EPO; JPO;	1
			DERWENT;	
			IBM_TDB	222 /21 /15 15 22
_	1372	adher\$4 with (protective passivation) with	USPAT;	2003/01/15 15:32
	20.2	(barrier metal)	US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			<pre>IBM_TDB USPAT;</pre>	2003/01/15 15:33
-	281	adher\$4 with ((protective passivation) adj	US-PGPUB;	2003/01/13 10:00
i	1	layer) with (barrier metal)	EPO; JPO;	
!	1		DERWENT;	
			IBM TDB	
i	36	adher\$4 with ((protective passivation) adj	USPĀT;	2003/01/15 16:46
-]	layer) with (barrier metal) and (bump	US-PGPUB;	[
		ball)	EPO; JPO;]
ľ			DERWENT;	
			IBM_TDB	2003/01/16 13:10
-	2	("6465582").PN.	USPAT;	2003/01/16 13:10
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
		(#C245250#) PN	USPAT;	2003/01/16 15:04
-	2	("6245259").PN.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
_	0	257/290-294.ccls. and (coating adj film)	USPAT;	2003/01/16 15:43
	1	near2 thickness with m	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	İ	11.512.3	IBM_TDB USPAT;	2003/01/16 15:44
_	0	257/290-294.ccls. and (coating adj film)	US-PGPUB;	2003/01/10 13:11
		with thickness with (m micrometer)	EPO; JPO;	
			DERWENT;	l i
Ì			IBM TDB	
	41	(chip die IC LED) and (coating adj film)	USPAT;	2003/01/16 20:14
_	1 41	with thickness with (m micrometer)	US-PGPUB;	
		With chizomos	EPO; JPO;	
			DERWENT;	
			IBM_TDB	2002 (01 (16 15:53
-	11234	(chip die IC LED lead wire) and (coating	USPAT;	2003/01/16 15:53
1		adj film)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	7.41
		(chip die IC LED lead wire) with (coating	USPAT;	2003/01/16 15:54
-	1987	(chip die ic LED lead wife) with (coating adj film)	US-PGPUB;	
		auj IIIMi	EPO; JPO;	
			DERWENT;	1
			IBM_TDB	
-	1324	(lead wire) with (coating adj film)	USPAT;	2003/01/16 15:54
	1327		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	2003/01/16 16:21
-	319	(lead wire) near2 (coating adj film)	USPAT; US-PGPUB;	2003/01/10 10:21
1			EPO; JPO;	
-			DERWENT;	
1			IBM TDB	
	1	(lead wire) near2 (coating adj film) and	USPAT;	2003/01/16 16:02
-	1	(amorphous adj fluororesin)	US-PGPUB;	
		/amarbusan and	EPO; JPO;	
			DERWENT;	
	1		IBM TDB	

	121	(lead wire) and (amorphous adj	USPAT;	2003/01/16 16:03
_	17		US-PGPUB;	
		fluororesin)	EPO; JPO;	1
			DERWENT;	
	1		IBM TDB	
	720	() decimal manual ((souting add film)	USPAT;	2003/01/16 16:23
-	730	(lead wire) near2 ((coating adj film)	US-PGPUB;	
		(plating adj layer))	EPO; JPO;	
1			DERWENT;	
1			IBM TDB	
		0 //	USPAT:	2003/01/16 16:28
-	47	lead\$4 near4 wir\$4 near2 ((coating adj	US-PGPUB;	2003, 01, 10 10:10
	1 1	film) (plating adj layer))	EPO; JPO;	
1]		DERWENT;	
			IBM TDB	
	1	5 //	USPAT;	2003/01/16 16:35
-	405	lead\$4 and wir\$4 near5 ((coating adj film)	US-PGPUB;	2003/01/10 10:33
		(plating adj layer))	EPO; JPO;	l
	1		DERWENT;	
			IBM TDB	
			USPAT;	2003/01/16 16:52
-	1	lead\$4 and wir\$4 near5 ((coating adj film)	USPAT; US-PGPUB;	2003/01/10 10:32
		(plating adj layer)) and (amorphous adj		
		fluororesin)	EPO; JPO; DERWENT;	
			IBM_TDB USPAT;	2003/01/21 13:12
-	26	, , =	US-PGPUB;	2003/01/21 13:12
		(micrometer um)	EPO; JPO;	
			DERWENT;	
			IBM TDB	1
			USPAT;	2003/01/16 20:25
-	2	("5221859").PN.	US-PGPUB;	2003/01/10 20:23
ļ			EPO; JPO;	}
			DERWENT;	
1	l l	I and the second	IBM TDB	

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